

# ChipDesign B.V.B.A.: RF IC Design Services & Antenna/MMIC Turn-Key Solutions

Koen Van Caekenberghe, Ph.D. ChipDesign B.V.B.A. E-Mail: info@chipdesign.be Cell: +32484836572

## ChipDesign B.V.B.A.



- ChipDesign B.V.B.A. is a private LLC according to Belgian law with VAT registration number: BE0501.767.340, founded in 2012. ChipDesign is located at Kapellelaan 302, 1860 Meise, Belgium.
- □ ChipDesign offers:
  - Services & turn-key solutions
    - ▷ ASIC design services
    - Device and process modeling services
    - > Turn-key solutions
  - Open-source software
    - ⊳ NF2FF
    - ⊳ rfMaxima
    - Verilog-A large-signal RF MEMS model library



- ChipDesign offers front-to-back mixed-signal / RFIC design services in triple-well bulk and twin-well PD- and FD-SOI/SOS CMOS processes, covering ASIC specification, design, layout, functional verification, packaging and characterization:
  - ASIC specification: performance versus power trade-off and partitioning across building blocks (Mathworks MATLAB & Simulink, Verilog-AMS, wxMaxima)
  - ASIC design:
    - Analog/RF: passive (antenna matching tuner, attenuator, (TTD) phase shifter, SPNT switch, transformer) and active (image-reject mixer, multiplier, LNA, PA, VCO) design. Analysis of non-linear circuits (HB, and (Q)PSS solvers) (Agilent GoldenGate, Cadence Spectre/RF, interested in Mentor Graphics Eldo and Synopsys HSPICE).
    - Digital: design (Verilog, VHDL) and synthesis (Cadence RTL Compiler and Synopsys Design Compiler). Integration of serial I/O interfaces (I<sup>2</sup>C, LVDS. RFFE, SPI) in ASICs.
    - EM: differential equation methods (FDTD, FEM), integral equation methods (TDIE, MoM/MLFMM). Interested in domain decomposition methods.
    - Mixed-signal: DAC (charge sharing, current steering), DDS, and PLL (PFD/CP, programmable divider, sigma/delta modulator) design. Interested in ADC and ADPLL design (BDA AFS, Cadence UltraSim).
    - Power management: AC-DC (voltage multiplier) and DC-DC (buck, boost, Dickson charge pump) converters, linear regulators (LDO, series), and voltage references (band gap).



- □ Front-to-back mixed-signal / RF IC design services (continued):
  - ASIC layout verification using DRC/LVS, parasitic extraction (Cadence Assura, Mentor Graphics Calibre), and EM simulation (Agilent Momentum, Ansys HFSS, CST Microwave Studio, Integrand EMX, Sonnet). IC yield optimization using foundry-supplied PCM data-based Monte Carlo and process corners simulation of extracted views.
  - RF IC floor planning (ESD protection, micro-bumps / pad ring, RF grounding) and RF IC packaging (DVN/QFN, WLCSP) and signal integrity analysis of PCB designs.
  - Mixed-signal ASIC functional verification using Verilog-AMS and digital ASIC/FPGA functional verification using SystemVerilog and UVM (Cadence Incisive).
  - On-wafer ASIC characterization, incl. large-signal S-parameter, noise (NF, phase noise), and non-linear measurements (ACPR, CSO, CTB, IP3, P1dB, XMOD). ASIC debugging (FIB).
  - Electronic design automation using Agilent AEL, Ansys VBScript, Cadence OCEAN, Python, ROD and SKILL, and Tcl.
- ChipDesign provides device and process modeling (Silvaco TCAD, Verilog-A) and characterization (Agilent IC-CAP) services:
  - III-V compound semiconductor (D/E-mode GaAs pHEMT, interested in GaN HEMT and InSb DHBT) and silicon-based (SiGe:C HBT) semiconductor devices
  - Capacitive MEMS and piezoelectric devices (accelerometers, gyroscopes, inertial measurement units, microphones, resonators (incl. quartz crystal, SAW and BAW resonators), switches)

- ChipDesign also offers turn-key RF solutions to customers. Examples include:
  - Antennas and antenna arrays
  - ASIC packages (BGA/LGA, DVN/QFN, SOT, WLCSP)
  - Class A through S PAs based on GaN or LDMOS transistors, incl. tunable matching networks for optimal load-pulling, as well as Doherty, EER (Kahn), ET and outphasing SSPA transmitters.
  - RF and mixed-signal PCB design and layout
  - PDK development



Figure 1: A differential RF MEMS reflectarray brick with 3:1 bandwidth (slotline RF MEMS TTD phase shifter DETSA) for a wideband brick assembled reflectarray for mobile backhaul applications.





ChipDesign uses and contributes to open-source EDA software in order to lower costs:

- NF2FF: NF2FF is a planar near-field to far-field transformation script, written in MATLAB, for antenna measurements. Near field (NF) ranges offer a convenient alternative to compact antenna test ranges (CATR) and anechoic far field ranges for the measurement of phased arrays. NF sites allow for hologram analysis, low sidelobes characterization, and do not require a rotating pedestal capable of bearing the weight of the phased array. The primary objective of the NF2FF sourceforge project is to provide the phased array community with an open-source MATLAB alternative to proprietary NF measurement software. The code features planar near field to far field transforms with rectangular waveguide probe correction. The secondary objective of the project is to implement various functions for phased array hologram analysis. Phased array holograms allow for faulty element localization and for measurement of active element amplitude and phase excitation, in transmit (Tx) as well as in receive (Rx) mode, which allows for insight in the difference between achieved and desired Tx and Rx array factor. In addition, active element Tx and Rx root mean square (RMS) amplitude and phase error can be measured which allows for insight in beam pointing error and side lobe level increase, and gain reduction, while scanning. http://nf2ff.sourceforge.net
- rfMaxima 0.2.4: rfMaxima is an RF toolbox for the wxMaxima computer algebra system. rfMaxima allows for symbolic derivation, as well as numerical evaluation (incl. Bode and Smith chart plotting), of 2-port network (ABCD, G, InverseABCD, H, S, Y, and Z), noise and stability parameters. Derivations are based on the solution of the set of Kirchoff current and voltage law equations representing the 2-port. Expressions can be exported to HTML or TeX. Figures can be exported to EPS or PNG. http://rfmaxima.sourceforge.net
- Verilog-A Large-Signal RF MEMS Model Library: The Verilog-A models can be used with SPICE solvers for DC, small-signal (AC, S-parameters) and large-signal (HB, PSS, QPSS) simulation of analog/RF circuits based on RF MEMS components (capacitors, resonators, switches, varactors). http://rfmems.sourceforge.net





### Near-Field to Far-Field Transformation for Antenna Measurements (NF2FF)

DOCUMENTATION DOWNLOAD SCREENSHOTS SUPPORT



Near field (NF) ranges offer a convenient alternative to compact antenna test ranges (CATR) and anechoic far field ranges for the measurement of phased arrays [1,2,3,4,5,6,7,8,9]. NF sites allow for hologram analysis, low sidelobes characterization, and do not require a rotating pedestal capable of bearing the weight of the phased array. The primary objective of the NF2FF sourceforge project is to provide the phased array community with an open-source MATLAB alternative to proprietary NF measurement software. The code features planar near field to far field transforms with rectangular waveguide probe correction. The secondary objective of the project is to implement various functions for phased array hologram analysis. Phased array holograms allow for faulty element localization [5] and for measurement of active element amplitude and phase excitation, in transmit (Tx) as well as in receive (Rx) mode, which allows for insight in the difference between achieved and desired Tx and Rx array factor. In addition, active element Tx and Rx root mean square (RMS) amplitude and phase error can be measured which allows for insight in beam pointing error and side lobe level increase, and gain reduction, while scanning [10].

Hologram analysis can also be used to study near field communication (NFC) antennas.



#### Assumptions

The script assumes:

- Rectangular coordinate system with z axis normal to planar aperture
- exp(j\*omega\*t) time dependence convention. Please, substitute i with -j whenever implementing exp(-i\*omega\*t) time dependence convention based algorithms.

#### Datasets

### Figure 2: nf2ff.sourceforge.net





- Example 15: Lossy transformer analysis
- Example 16: <u>Waveguide loss (TE<sub>10</sub> mode) notebook</u>

#### **Planned extensions**

Figure 3: rfmaxima.sourceforge.net

ChipDesign's Open-Source Software: Verilog-A RF MEMS Model Library



softening, and van der Waals interaction. In addition, noise sources, such as Brownian noise sources and thermal noise sources, are also modeled. Other multiphysics effects, such as acoustoelectric, electrothermal, piezoelectric, pyroelectric and thermomechanical effects, are not included yet.

The Verilog-A models can be used with SPICE solvers for DC, small-signal (AC, noise, S-parameters (SP)) and large-signal (harmonic balance (HB), periodic steady-state (PSS), quasiperiodic steady-state (QPSS), transient) simulation of analog/RF circuits based on RF MEMS components. Some remarks on simulation:

- Large-signal simulation (1 dB compression point, third order intercept) of high-Q resonator based analog/RF circuits: While transient analysis is feasible, it requires a large number of time steps to reach the steady-state regime. It is therefore recommended to use the HB method, which directly converges to the steady-state solution, with a limited number of harmonics.
- Noise simulation: Supply-voltage noise should be generated by the test bench.
- Power consumption simulation: At rest, electrostatically-actuated RF MEMS capacitors and switches exhibit no static (DC) power consumption. While switching, electrostaticallyactuated RF MEMS capacitors and switches do exhibit dynamic (AC) power consumption (10-100 nJ per switching cycle). The dynamic power consumption is due to current transients, which (dis)charge the capacitive transducer. It is therefore recommended to perform a transient simulation.
- Switching time simulation of switch based analog/RF circuits: RF MEMS switches are slow compared to III-V compound semiconductor and silicon semiconductor switches. It is therefore recommended to perform an envelope simulation.

The Verilog-A models allow for specification of beam dimensions and material properties (Poisson ratio, Young's modulus, etc...). Examples of schematics based on gallium nitride (GaN), polysilicon, silicon carbide (SiC) fixed-fixed beam RF MEMS resonators and oscillators, as well as golden capacitive fixed-fixed beam and ohmic cantilever RF MEMS switches, are available upon request. A user guide is being written.

Figure 4: rfmems.sourceforge.net

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How to install the 1-DOF Verilog-A compact models: □ Agilent ADS:

- Copy the files with *ael* extension into the *networks* subdirectory of the ADS project.
- If necessary, make a *veriloga* subdirectory in the ADS project.
- Copy the files with va extension into the veriloga subdirectory of the ADS project.
- Close and reopen the ADS project.
- Create a new design.
- Insert a random component and swap it with

FIXED\_FIXED\_BEAM\_RF\_MEMS\_RESONATOR or

FREE\_FREE\_BEAM\_RF\_MEMS\_RESONATOR.

- □ Cadence Virtuoso Schematic Editor:
  - CIW: File  $\rightarrow$  New  $\rightarrow$  Cellview...
  - Create New File: Cell Name: FIXED\_FIXED\_BEAM\_RF\_MEMS\_RESONATOR or FREE\_FREE\_BEAM\_RF\_MEMS\_RESONATOR, View Name: veriloga, Tool: VerilogA-Editor. Click "OK".
  - The editor will appear. Copy/paste the Verilog-A code into the editor. Save it and exit the editor.
  - A dialog box will appear and ask you if you want to create a new symbol. Click "Yes".
  - The Symbol Generation Options window will appear. Make appropriate changes and click "OK".
  - Create a new schematic and insert an instance of the FIXED\_FIXED\_BEAM\_RF\_MEMS\_RESONATOR component or the FREE\_FREE\_BEAM\_RF\_MEMS\_RESONATOR component.

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## Acronyms



	MIMO
ACLR adjacent channel leakage ratio	MOCVI
ADC analog to digital converter	MMMB
AESA active electronically scanned array	LNA
AMS analog-mixed signal	LTE
AMT antenna matching tuner	LTE-A
ASM antenna switch module	PA
BAW bulk acoustic wave	PAE
BEOL back end of line	РСМ
BT bluetooth	PDK
BTO barium titanate	PD-SO
CA carrier aggregation	PESA
CMOS complementary metal oxide semiconductor	PMIC
CPU central processing unit	PLD
CRF coupled resonator filter	PSS
CSD chemical solution deposition	PVT
DDS direct digital synthesizer	PZT
DMS dual mode SAW	Q
DPX duplexer	QFN
DSP digital signal processor	QPSS
EMI electromagnetic interference	QS
EVM error vector magnitude	RF
ET envelope tracking	RF IC
FBAR film bulk acoustic resonator	RSSI
FDD frequency division duplex	RX
FD-SOI fully-depleted silicon-on-insulator	SAR
FEA finite element analysis	SAW
FEM front-end module	SKU
GPU graphical processing unit	SMR
GSM global system for mobile communications	SMT
HB harmonic balance	SNR
HBT heterojunction bipolar transistor	SoC
HDL hardware description language	SPNT
HETNET heterogeneous network	TDD
IC integrated circuit	ТΧ
IEEE institute for electrical and electronics engineers	UMTS
IL insertion loss	VSWR
IP intellectual property	WLAN
MBE molecular beam epitaxy	WLCSF
MEMS micro electromechanical system	WPAN

MIMO MOCVD	multiple-in multiple-out metallo-organic chemical vapor deposition
MMMB	multi mode multi band
_NA	low noise amplifier
TE	long term evolution
_TE-A	long term evolution - advanced
PA	power amplifiers
PAE	power added efficiency
PCM	process control monitor
PDK	process development kit
PD-SOI	partially-depleted silicon-on-insulator
PESA	passive electronically scanned array
PMIC	power management integrated circuit
PLD	pulsed laser deposition
PSS	periodic steady state
PVT	process voltage temperature
PZT	lead zirconate titanate
<b>ર</b>	quality factor
QFN	quad-flat no-leads
QPSS	quasi-periodic steady-state
ຊຸຣ	quasi-static
RF	radio frequency
RF IC	radio frequency integrated circuit
RSSI	received signal strength indicator
RX	receiver
SAR	specific absorption rate
SAW	surface acoustic wave
SKU	stock keeping unit
SMR	solidly mounted resonator
SMT	surface mount technology
SNR	signal to noise ratio
SoC	system-on-chip
SPNT	single pole N throw
TDD	time division duplex
IX	transmitter
JMTS	universal mobile telecommunication system
VSWR	voltage standing wave ratio
WLAN	wireless local area network
WLCSP	water level chip scale package

wireless personal area network